南京时恒电子科技有限公司

规格承认书

APPROVAL SHEET

客户名称：

CUSTOMER _____

产品名称：

PART NAME 片式 NTC 热敏电阻规格书

产品规格：

PART NUMBER CMFB 104F3950

日期：

DATE 2021 年 3 月 29 日

确 认

CONFIRM

客户	供货商/制造商
品保部：_____	规格书制作：鞠晓丽
制造部：_____	业务员审核：_____
工程部：_____	技术部审核：程鹏 品质部审核：李竹媛

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1.外形尺寸　Shape and Dimensions

- 尺寸：见图 1 和表 1　　Dimensions: See Fig.1 and Table 1.
- PCB 焊盘：见图 2 和表 1　　Recommended PCB pattern for reflow soldering: See Fig.2 and Table 1.

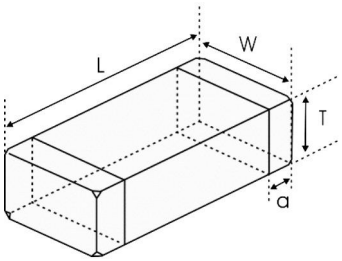


图 1 Fig.1

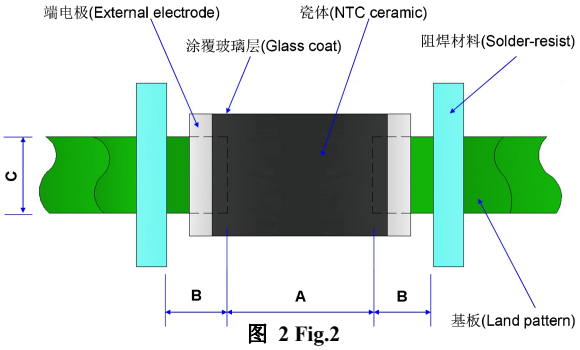


图 2 Fig.2

表 1（Table 1）　　单位 unit: inch[mm]

类别Type	L	W	T	a	A	B	C
B [0805]	0.079±0.008 [2.0±0.2]	0.049±0.008 [1.25±0.2]	0.033±0.008 [0.85±0.2]	0.020±0.012 [0.5±0.3]	[1.0-1.1]	[0.6-0.7]	[10.-1.2]

2 产品标识（料号） Product Identification(Part Number)

CMF ① B ② 104 ③ F ④ 3950 ⑤

①类别 Type	
CMF	片式NTC 热敏电阻器 Chip NTC Thermistor

② 外形尺寸(mm) External Dimensions (L×W)	
A	1.6×0.8
B	2.0×1.2

③25℃的零功率电阻 Nominal Zero-Power Resistance	
222	2.2kΩ
103	10kΩ
104	100kΩ

④电阻值公差 Tolerance of Resistance	
F	±1%
G	±2%
H	±3%
J	±5%

⑤B 值常数 B Constant	
3435	3435K
3950	3950K
4250	4250K

3 电气特性 Electrical Characteristics

型号 Part No	电阻值 Resistance (25℃) (kΩ)	B 常数B Constant (25/50℃) （K）	B 常 数 B Constant (25/85℃) （K）	允许工作电流 Permissible Operating Current (25℃) （mA）	耗散系数 Dissipation Factor (mW/℃)	热时间常数 Thermal Time Constant (s)	额定功率 Rated Electric Power(25℃) (mW)	工作温度 Operating ambient temperature (℃)
CMFB 104F3950	100	3950	3987	0.14	1.0	<5	100	-40～+125

4 检验和测试程序

测试条件

如无特别规定，检验和测试的标准大气环境条件如下：

a. 环境温度：20±15℃；
b. 相对湿度：65±20%；
c. 气压：86 kPa~106 kPa

如果对测试结果有异议，则在下述条件下测试：

a. 环境温度：20±2℃；

b. 相对湿度：65±5%RH；

c. 气压：86kPa ~ 106kPa

检查设备

外观检查：20 倍放大镜；

阻值检查：热敏电阻测试仪

4 Test and Measurement Procedures

Test Conditions

Unless otherwise specified, the standard atmospheric conditions for measurement/test as:

a. Ambient Temperature: 20±15℃

b. Relative Humidity : 65±20%

c. Air Pressure: 86kPa to 106kPa

If any doubt on the results, measurements/tests should be made within the following limits:

a. Ambient Temperature: 20±2℃

b. Relative Humidity: 65±5%

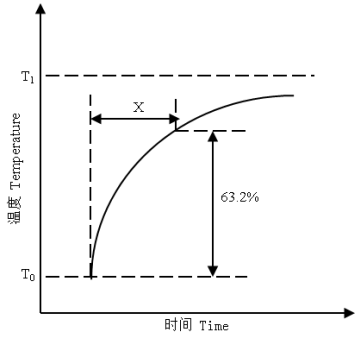
c. Air Pressure: 86kPa to 106kPa

Inspection Equipment

Visual Examination: 20×magnifier

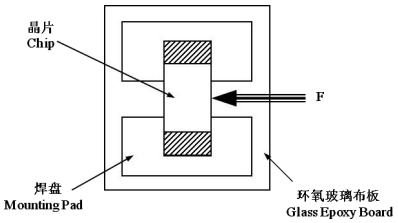
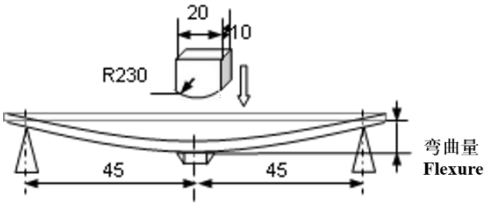
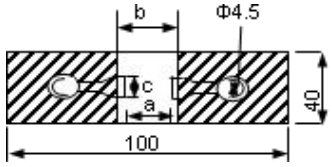
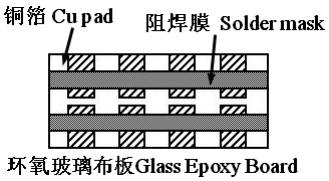
Resistance value test: Thermistor resistance tester

5 电性测试 Electrical Test

序号 No.	项目 Items	测试方法及备注 Test Methods and Remarks
1	25℃零功率电阻值 Nominal Zero-Power Resistance at 25℃ (R25)	环境温度 Ambient temperature：25±0.2℃ 测试功率 Measuring electric power：≤0.1mW
2	B 值常数 Nominal B Constant	分别在环境温度 25±0.2℃， 50±0.2℃或 85±0.2℃下测量电阻值。 Measure the resistance at the ambient temperature of 25±0.2℃ , 50±0.2℃ or 85±0.2℃. $B(25\text{-}50℃)=\frac{\ln R25-\ln R50}{T_{25}^{-1}-T_{50}^{-1}}$ $B(25\text{-}85℃)=\frac{\ln R25-\ln R85}{1/T_{25}-1/T_{85}}$ T：绝对温度（K）Absolute temperature (K)
3	热时间常数 Thermal Time Constant	在零功率条件下，当热敏电阻的环境温度发生急剧变化时，热敏电阻元件产生最初温度 T0 与最终温度 T1 两者温度差的 63.2%的温度变化所需要的时间，通常以秒(S)表示。 The total time for the temperature of the thermistor to change by 63.2% of the difference from ambient temperature T_0 (℃) to T_1 (℃) by the drastic change of the power applied to thermistor from Non-zero Power to Zero-Power state, normally expressed in second(S). 
4	耗散系数 Dissipation Factor	在一定环境温度下，NTC 热敏电阻通过自身发热使其温度升高 1℃时所需要的功率，通常以 mW/℃表示。可由下面公式计算： The required power which makes the NTC thermistor body temperature raise 1 ℃ through self-heated, normally expressed in milliwatts per degree Celsius (mW/ ℃). It can be calculated by the following formula: $\delta=\frac{W}{T-T_0}$

5	额定功率 Rated Power	在环境温度 25℃下因自身发热使表面温度升高 100℃所需要的功率。 The necessary electric power makes thermistor's temperature rise 100℃ by self-heating at ambient temperature 25℃.
6	允许工作电流 Permissible operating current	在静止空气中通过自身发热使其升温为 1℃的电流。 The current that keep body temperature of chip NTC on the PC board in still air rising 1°C by self-heating.

6 信赖性试验 Reliability Test

项目 Items	测试标准 Standard	测试方法及备注 Test Methods and Remarks	要求 Requirements
端头附着力 Terminal Strength	IEC 60068-2-21	① 将晶片焊接在测试基板上（如右图所示的环氧玻璃布板），按箭头所示方向施加作用力； Solder the chip to the testing jig (glass epoxy board shown in the right) using eutectic solder. Then apply a force in the direction of the arrow. ② 0201、 X 和 A 系列施加 5N 的作用力， B 系列产品施加 10N 的作用力； 5N force for 0201, Xand A series, 10N force for B series. ③ 保持时间 Duration：10±1s	端电极无脱落且瓷体无损伤。 No removal or split of the termination or other defects shall occur. 
抗弯强度 Resistance to Flexure	IEC 60068-2-21	① 将晶片焊接在测试基板上（如右图所示的环氧玻璃布板），按下图箭头所示方向施加作用力； Solder the chip to the test jig (glass epoxy board shown in the right) using a eutectic solder. Then apply a force in the direction shown as follow; ② 弯曲变形量 Flexure 0201: 1mm X, A, B: 2mm ③ 施压速度 Pressurizing Speed：＜0.5mm/s； ④ 保持时间 Duration：10s 	① 无外观损伤。 No visible damage. ② 试验前后 R25 的变化率：±5%以内； R25 variation: within ±5% 单位 unit：mm 类型 Type | a | b | c 0201 | 0.25 | 0.3 | 0.3 X | 0.4 | 1.5 | 0.5 A | 1.0 | 3.0 | 1.2 B | 1.2 | 4.0 | 1.65 
振动 Vibration	IEC 60068-2-80	① 将晶片焊接在测试基板上（如右图所示的环氧玻璃布板）； Solder the chip to the testing jig (glass epoxy board shown in the left) using eutectic solder. ② 晶片以全振幅为 1.5mm 进行振动， 频率范围为 10Hz ～55 Hz； The chip shall be subjected to a simple harmonic motion having total amplitude of 1.5mm, the frequency being varied uniformly between the approximate limits of 10 and 55 Hz. ③ 振动频率按 10Hz→55Hz→10Hz 循环，周期为 1 分钟，在空间三个互相垂直的方向上各振动 2 小时（共 6 小时）。 The frequency ranges from 10 to 55 Hz and return to 10 Hz shall be traversed in approximately 1 minute. This motion shall be applied for a period of 2 hours in	无外观损伤。 No visible damage. 

<table>
<tr><td></td><td></td><td>each 3mutually perpendicular directions (total of 6 hours).</td><td></td></tr>
<tr><td>坠落
Dropping</td><td>IEC 60068-2-32</td><td>从 1m 的高度让晶片自由坠落至水泥地面 10 次。
Drop a chip 10 times on a concrete floor from a height of 1 meter.</td><td>无外观损伤。
No visible damage.</td></tr>
<tr><td>可焊性
Solderability</td><td>IEC 60068-2-58</td><td>① 焊接温度 Solder temperature: 245±5℃.
② 浸渍时间 Duration: 3±0.3s.
③ 焊锡成分 Solder: Sn/3.0Ag/0.5Cu.
④ 助焊剂 Flux: （重量比）25%松香和 75%酒精
25% Resin and 75% ethanol in weight.</td><td>① 无外观损伤；
No visible damage.
② 元件端电极的焊锡覆盖率不小于 95%。
Wetting shall exceed 95% coverage.</td></tr>
<tr><td>耐焊性
Resistance to Soldering Heat</td><td>IEC 60068-2-58</td><td>① 焊接温度 Solder temperature: 260±5℃.
② 浸渍时间 Duration: 10±1s.
③ 焊锡成分 Solder: Sn/3.0Ag/0.5Cu.
④ 助焊剂 Flux: （重量比）25%松香和 75%酒精
25% Resin and 75% ethanol in weight.
⑤ 试验后标准条件下放置 1~2 小时后测量。
The chip shall be stabilized at normal condition for 1~2 hours before measuring.</td><td>① 无外观损伤；
No visible damage.
② 试验前后 R25 的变化率：±3%以内；
R25 variation: within ±3%
③ 试验前后 B 值的变化率：±2%以内。
B constant variation: within ±2%</td></tr>
<tr><td>温度周期
Temperature cycling</td><td>IEC 60068-2-14</td><td>① 无负载于下表所示的环境条件下重复 5 次。
5 cycles of following sequence without loading.
<table>
<tr><th>步骤 Step</th><th>温度 Temperature</th><th>时间 Time</th></tr>
<tr><td>1</td><td>-40±5℃</td><td>30±3min</td></tr>
<tr><td>2</td><td>25±2℃</td><td>5±3min</td></tr>
<tr><td>3</td><td>125±2℃</td><td>30±3min</td></tr>
<tr><td>4</td><td>25±2℃</td><td>5±3min</td></tr>
</table>
② 试验后标准条件下放置 1~2 小时后测量。
The chip shall be stabilized at normal condition for 1~2 hours before measuring.</td><td>① 无外观损伤；
No visible damage.
② 试验前后 R25 的变化率：±3%以内；
R25 variation: within ±3%
③ 试验前后 B 值的变化率：±2%以内。
B constant variation: within ±2%</td></tr>
<tr><td>高温存放
Resistance to dry heat</td><td>IEC 60068-2-2</td><td>① 在 125±5℃空气中，无负载放置 1000±24 小时。
125±5℃ in air, for 1000±24 hours without loading.
② 试验后标准条件下放置 1~2 小时后测量。
The chip shall be stabilized at normal condition for 1~2 hours before measuring.</td><td>① 无外观损伤；
No visible damage.
② 试验前后 R25 的变化率：±5%以内；
R25 variation: within ±5%
③ 试验前后 B 值的变化率：±2%以内。
B constant variation: within ±2%</td></tr>
<tr><td>低温存放
Resistance to cold</td><td>IEC 60068-2-1</td><td>① 在-40±3℃空气中，无负载放置 1000±24 小时。
-40±3℃ in air, for 1000±24 hours without loading.
② 试验后标准条件下放置 1~2 小时后测量。
The chip shall be stabilized at normal condition for 1~2 hours before measuring.</td><td>① 无外观损伤；
No visible damage.
② 试验前后 R25 的变化率：±5%以内；
R25 variation: within ±5%
③ 试验前后 B 值的变化率：±2%以内。
B constant variation: within ±2%</td></tr>
<tr><td>湿热存放
Resistance to damp heat</td><td>IEC 60068-2-78</td><td>① 在 40±2℃，相对湿度 90~95%空气中，无负载放置 1000±24 小时。
40±2℃, 90~95%RH in air, for 1000±24 hours without loading.
② 试验后标准条件下放置 1~2 小时后测量。
The chip shall be stabilized at normal condition for 1~2 hours before measuring.</td><td>① 无外观损伤；
No visible damage.
② 试验前后 R25 的变化率：±3%以内；
R25 variation: within ±3%
③ 试验前后 B 值的变化率：±2%以内。
B constant variation: within ±2%</td></tr>
</table>

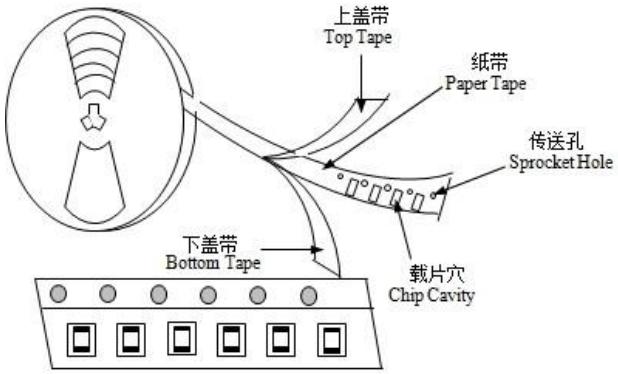
高温负荷 Resistance to high temperature load	IEC 60539-1 5.25.4	① 在85±2℃空气中，施加允许工作电流1000±48小时。 85±2℃in air with permissive operating current for 1000±48 hours ② 试验后标准条件下放置 1~2 小时后测量。 The chip shall be stabilized at normal condition for 1~2 hours before measuring.	① 无外观损伤； No visible damage. ② 试验前后 R25 的变化率：±5%以内； R25 variation: within ±5% ③ 试验前后 B 值的变化率：±2%以内。 B constant variation: within ±2%

7 编带和储存 Taping & Storage

编带 Taping

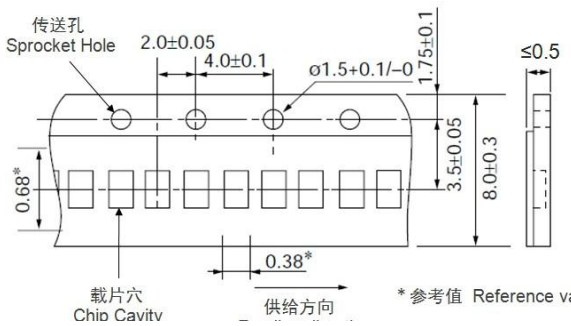
类型 Type	0201	X	A	B
编带厚度 Tape thickness(mm)	0.5±0.15	0.5±0.15	0.8±0.15	0.85±0.2
编带材质 Tape material	纸 带 Paper Tape			
每盘数量 Quantity per Reel	15K	10K	4K	4K

(1) 编带图 Taping Drawings

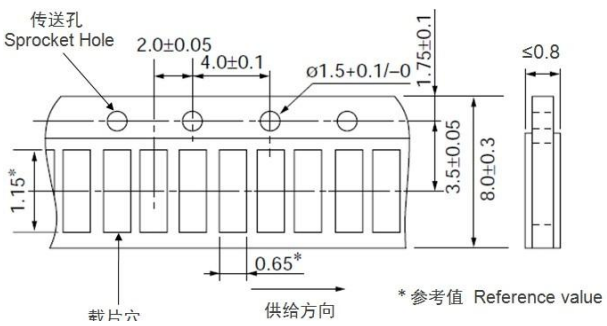


(2) 纸带尺寸 Paper Tape Dimensions (单位 Unit：mm)

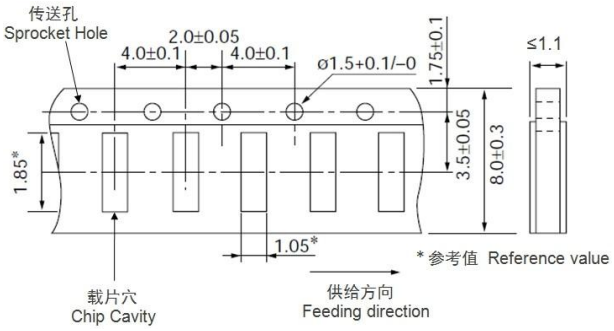
0201 系列 0201 series



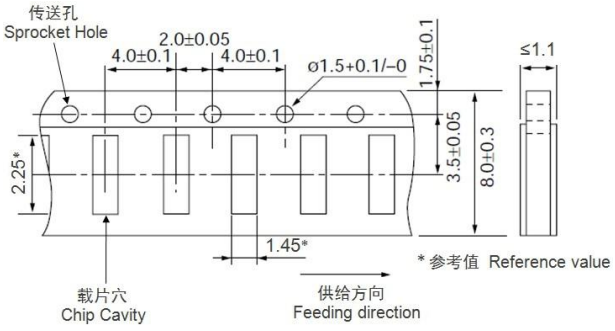
X 系列 X series



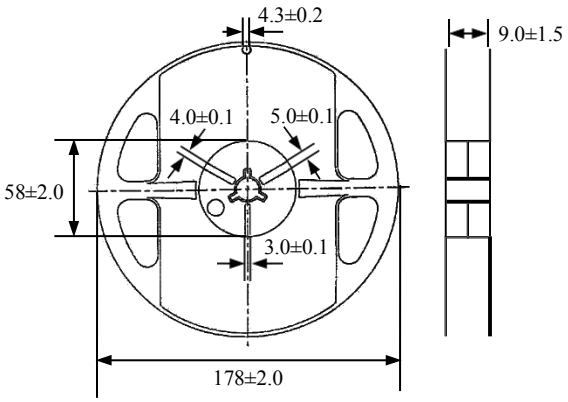
A 系列 A series

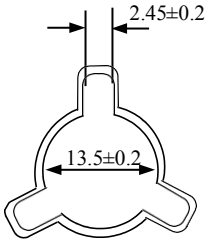


B 系列 B series



(3) 卷盘尺寸 Reel Dimensions(单位 Unit：mm)





8 储存

- **储存条件**

a. 储存温度：-10℃～40℃

b. 相对湿度：≤75%RH

c. 避免接触粉尘、腐蚀性气氛和阳光

- **储存期限：6 个月**

9 注意事项

- 系列热敏电阻不可在以下条件下工作或储存：

(1) 腐蚀性气体或还原性气体

(氯气、硫化氢气体、氨气、硫酸气体、一氧化氮等)。

(2) 挥发性或易燃性气体

(3) 多尘条件

(4) 高压或低压条件

(5) 潮湿场所

(6) 存在盐水、油、化学液体或有机溶剂的场所

(7) 强烈振动

(8) 存在类似有害条件的其他场所

- 系列热敏电阻的陶瓷属于易碎材料，使用时不可施加过大压力或冲击。

- 系列热敏电阻不可在超过目录规定的温度范围情况下工作。

8 Storage

- **Storage Conditions**

a. Storage Temperature: -10℃～40℃

b. Relative Humidity: ≦75%RH

c. Keep away from corrosive atmosphere and sunlight.

- **Period of Storage**: **6 Months**

9 Notes ＆ Warnings

- The series thermistors shall not be operated and stored under the following environmental condition:

(1) Corrosive or deoxidized atmospheres

(such as chlorine, sulfurated hydrogen, ammonia, sulfuric acid, nitric oxide and so on)

(2) Volatile or inflammable atmospheres

(3) Dusty condition

(4) Excessive high or low pressure condition

(5) Humid site

(6) Places with brine, oil, chemical liquid or organic solvent

(7) Intense vibration

(8) Places with analogously deleterious conditions

- The ceramic body of the series thermistors is fragile, no excessive pressure or impact shall be exerted on it.

- The series thermistors shall not be operated beyond the specified “Operating Temperature Range” in the catalog.

10 建议焊接条件

- **回流焊**

温升 1~2℃/sec.

预热：150~190℃/90±30 sec.

大于 240℃时间：20~40sec

峰值温度：最高 260℃/10 sec.

焊锡：Sn/3.0Ag/0.5Cu

回流焊：最多 2 次

10Recommended Soldering Technologies

- **Re-flowing Profile**

1~2 ℃/sec. Ramp

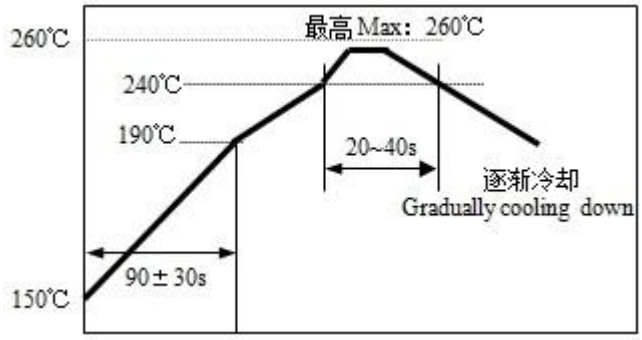
Pre-heating: 150~190℃/90±30 sec.

Time above 240℃: 20~40 sec.

Peak temperature: 260℃Max./10 sec.

Solder paste: Sn/3.0Ag/0.5Cu

Max.2 times for re-flowing.



- **手工焊**

烙铁功率：最大 30W

预热：150 ℃/60 sec.

烙铁头温度：最高 350℃

焊接时间：最多 3sec.

焊锡：Sn/3.0Ag/0.5Cu

手工焊：最多 1 次

[注：不要使烙铁头接触到端头]

- **Iron Soldering Profile**

Iron soldering power: Max.30W

Pre-heating: 150℃/60 sec.

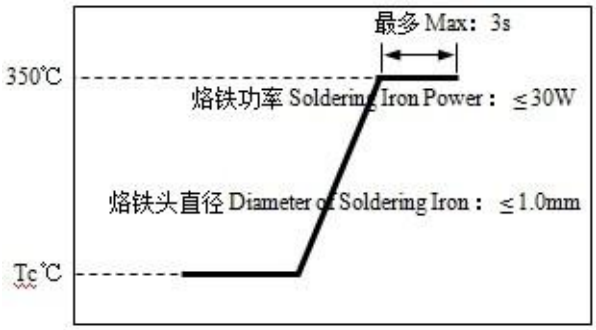
Soldering Tip temperature: 350℃Max.

Soldering time: 3 sec Max.

Solder paste: Sn/3.0Ag/0.5Cu

Max.1 times for iron soldering

[Note: Take care not to apply the tip of the soldering iron to the terminal electrodes.]



11R-T 表 R-T table

温度 Temp. (℃)	R 最小值 R_Min (Kohm)	R 中心值 R_Cent (Kohm)	R 最大值 R_Max (Kohm)	阻值公差 Res TOL.	温度公差 Temp. TOL.(℃)
-40	3,299.275	3,452.748	3,613.000	4.64%	0.67
-39	3,086.507	3,227.909	3,375.451	4.57%	0.66
-38	2,888.916	3,019.247	3,155.143	4.50%	0.66
-37	2,705.320	2,825.494	2,950.711	4.43%	0.65
-36	2,534.636	2,645.486	2,760.908	4.36%	0.65
-35	2,375.874	2,478.161	2,584.594	4.29%	0.64
-34	2,228.123	2,322.542	2,420.720	4.23%	0.64
-33	2,090.549	2,177.736	2,268.333	4.16%	0.63
-32	1,962.386	2,042.922	2,126.550	4.09%	0.63
-31	1,842.930	1,917.347	1,994.569	4.03%	0.62
-30	1,731.535	1,800.319	1,871.649	3.96%	0.61
-29	1,627.605	1,691.203	1,757.110	3.90%	0.61
-28	1,530.593	1,589.414	1,650.330	3.83%	0.60
-27	1,439.996	1,494.413	1,550.732	3.77%	0.60
-26	1,355.349	1,405.707	1,457.791	3.71%	0.59
-25	1,276.225	1,322.839	1,371.019	3.64%	0.59
-24	1,202.069	1,245.222	1,289.795	3.58%	0.58
-23	1,132.704	1,172.662	1,213.908	3.52%	0.58
-22	1,067.789	1,104.798	1,142.976	3.46%	0.57
-21	1,007.012	1,041.298	1,076.644	3.39%	0.56
-20	950.083	981.854	1,014.586	3.33%	0.56
-19	896.736	926.182	956.500	3.27%	0.55
-18	846.723	874.020	902.107	3.21%	0.55
-17	799.816	825.125	851.151	3.15%	0.54
-16	755.802	779.274	803.393	3.10%	0.53
-15	714.487	736.257	758.614	3.04%	0.53
-14	675.688	695.883	716.610	2.98%	0.52
-13	639.237	657.974	677.193	2.92%	0.51
-12	604.978	622.365	640.187	2.86%	0.51
-11	572.767	588.902	605.432	2.81%	0.50
-10	542.468	557.444	572.776	2.75%	0.49
-9	513.958	527.858	542.081	2.69%	0.49
-8	487.119	500.023	513.217	2.64%	0.48
-7	461.844	473.824	486.065	2.58%	0.47
-6	438.034	449.155	460.513	2.53%	0.47
-5	415.595	425.920	436.458	2.47%	0.46
-4	394.410	403.995	413.772	2.42%	0.45
-3	374.434	383.332	392.403	2.37%	0.45
-2	355.589	363.850	372.266	2.31%	0.44
-1	337.807	345.475	353.283	2.26%	0.43
0	321.020	328.139	335.382	2.21%	0.43
1	305.185	311.793	318.513	2.16%	0.42

2	290.224	296.357	302.590	2.10%	0.41
3	276.083	281.775	287.557	2.05%	0.40
4	262.713	267.995	273.357	2.00%	0.40
5	250.067	254.969	259.940	1.95%	0.39
6	238.082	242.628	247.236	1.90%	0.38
7	226.741	230.956	235.227	1.85%	0.37
8	216.007	219.915	223.872	1.80%	0.37
9	205.845	209.467	213.132	1.75%	0.36
10	196.220	199.576	202.969	1.70%	0.35
11	187.106	190.215	193.357	1.65%	0.34
12	178.469	181.348	184.255	1.60%	0.33
13	170.278	172.943	175.632	1.55%	0.33
14	162.511	164.976	167.462	1.51%	0.32
15	155.141	157.420	159.718	1.46%	0.31
16	148.144	150.250	152.372	1.41%	0.30
17	141.502	143.448	145.406	1.37%	0.29
18	135.195	136.991	138.797	1.32%	0.29
19	129.205	130.862	132.526	1.27%	0.28
20	123.514	125.041	126.574	1.23%	0.27
21	118.106	119.511	120.922	1.18%	0.26
22	112.964	114.257	115.554	1.13%	0.25
23	108.075	109.264	110.454	1.09%	0.24
24	103.425	104.515	105.607	1.04%	0.24
25	99.000	100.000	101.000	1.00%	0.23
26	94.705	95.704	96.704	1.04%	0.24
27	90.621	91.617	92.614	1.09%	0.25
28	86.735	87.726	88.719	1.13%	0.26
29	83.036	84.021	85.009	1.18%	0.27
30	79.516	80.493	81.475	1.22%	0.29
31	76.164	77.133	78.107	1.26%	0.30
32	72.972	73.932	74.897	1.31%	0.31
33	69.931	70.881	71.837	1.35%	0.32
34	67.034	67.973	68.918	1.39%	0.33
35	64.272	65.199	66.133	1.43%	0.35
36	61.638	62.554	63.476	1.47%	0.36
37	59.127	60.030	60.941	1.52%	0.37
38	56.732	57.621	58.519	1.56%	0.38
39	54.446	55.322	56.207	1.60%	0.40
40	52.264	53.127	53.999	1.64%	0.41
41	50.181	51.030	51.889	1.68%	0.42
42	48.193	49.028	49.873	1.72%	0.43
43	46.294	47.115	47.945	1.76%	0.45
44	44.479	45.285	46.102	1.80%	0.46
45	42.745	43.537	44.340	1.84%	0.47

46	41.089	41.867	42.656	1.88%	0.49
47	39.507	40.270	41.045	1.92%	0.50
48	37.993	38.743	39.503	1.96%	0.51
49	36.546	37.281	38.027	2.00%	0.53
50	35.161	35.882	36.614	2.04%	0.54
51	33.836	34.543	35.261	2.08%	0.55
52	32.567	33.260	33.965	2.12%	0.57
53	31.353	32.032	32.723	2.16%	0.58
54	30.190	30.856	31.533	2.19%	0.59
55	29.076	29.729	30.392	2.23%	0.61
56	28.010	28.649	29.299	2.27%	0.62
57	26.988	27.613	28.251	2.31%	0.64
58	26.008	26.620	27.245	2.35%	0.65
59	25.069	25.669	26.280	2.38%	0.66
60	24.168	24.755	25.355	2.42%	0.68
61	23.306	23.881	24.468	2.46%	0.69
62	22.479	23.042	23.616	2.49%	0.71
63	21.686	22.237	22.799	2.53%	0.72
64	20.925	21.464	22.014	2.57%	0.74
65	20.194	20.721	21.261	2.60%	0.75
66	19.491	20.007	20.535	2.64%	0.76
67	18.816	19.321	19.838	2.67%	0.78
68	18.167	18.661	19.167	2.71%	0.79
69	17.544	18.028	18.523	2.75%	0.81
70	16.946	17.419	17.903	2.78%	0.82
71	16.374	16.836	17.310	2.82%	0.84
72	15.824	16.276	16.740	2.85%	0.85
73	15.295	15.738	16.192	2.88%	0.87
74	14.786	15.220	15.664	2.92%	0.88
75	14.298	14.721	15.156	2.95%	0.90
76	13.826	14.240	14.666	2.99%	0.92
77	13.372	13.777	14.194	3.02%	0.93
78	12.935	13.332	13.739	3.06%	0.95
79	12.515	12.903	13.301	3.09%	0.96
80	12.110	12.490	12.880	3.12%	0.98
81	11.722	12.093	12.475	3.16%	0.99
82	11.348	11.711	12.084	3.19%	1.01
83	10.988	11.343	11.708	3.22%	1.03
84	10.641	10.988	11.346	3.26%	1.04
85	10.306	10.646	10.996	3.29%	1.06
86	9.984	10.316	10.659	3.32%	1.07
87	9.673	9.999	10.334	3.35%	1.09
88	9.374	9.692	10.020	3.38%	1.11
89	9.085	9.396	9.717	3.42%	1.12

90	8.806	9.111	9.425	3.45%	1.14
91	8.538	8.836	9.143	3.48%	1.16
92	8.279	8.570	8.871	3.51%	1.17
93	8.029	8.314	8.609	3.54%	1.19
94	7.787	8.066	8.355	3.57%	1.21
95	7.555	7.828	8.110	3.61%	1.22
96	7.330	7.598	7.874	3.64%	1.24
97	7.114	7.376	7.646	3.67%	1.26
98	6.906	7.162	7.427	3.70%	1.27
99	6.704	6.955	7.214	3.73%	1.29
100	6.509	6.755	7.008	3.76%	1.31
101	6.321	6.561	6.810	3.79%	1.33
102	6.139	6.374	6.618	3.82%	1.34
103	5.963	6.194	6.432	3.85%	1.36
104	5.793	6.019	6.252	3.88%	1.38
105	5.629	5.850	6.079	3.91%	1.40
106	5.470	5.686	5.910	3.94%	1.41
107	5.317	5.528	5.747	3.97%	1.43
108	5.168	5.375	5.590	4.00%	1.45
109	5.025	5.227	5.438	4.03%	1.47
110	4.886	5.084	5.290	4.05%	1.49
111	4.751	4.945	5.147	4.08%	1.50
112	4.620	4.811	5.009	4.11%	1.52
113	4.494	4.681	4.875	4.14%	1.54
114	4.372	4.555	4.745	4.17%	1.56
115	4.254	4.433	4.619	4.20%	1.58
116	4.141	4.316	4.498	4.22%	1.60
117	4.030	4.202	4.381	4.25%	1.62
118	3.923	4.092	4.267	4.28%	1.63
119	3.820	3.985	4.157	4.31%	1.65
120	3.720	3.881	4.050	4.34%	1.67
121	3.622	3.781	3.946	4.36%	1.69
122	3.528	3.684	3.845	4.39%	1.71
123	3.437	3.589	3.748	4.42%	1.73
124	3.349	3.498	3.653	4.44%	1.75
125	3.263	3.409	3.562	4.47%	1.77